

DOCKET NO. 93-C-077C1 (STMI01-93077)

Customer No. 30425

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re application of : Loi N. Nguyen, et al.

U.S. Serial No. : 09/712,827

Filed : November 14, 2000

For : METHOD AND INTERLEVEL DIELECTRIC STRUCTURE  
FOR IMPROVED METAL STEP COVERAGE

Group No. : 2835

Examiner : L. Pham

**BOX NON-FEE AMENDMENT**

Commissioner for Patents  
Washington, D. C. 20231

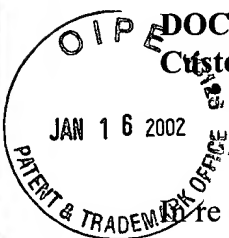
Sir:

**RESPONSE TO RESTRICTION REQUIREMENT**

In response to the Restriction Requirement mailed October 12, 2001, Applicants provisionally elect the claims of Group I, claims 35-41 and 49-53, WITH TRAVERSE.

The Office Action states: "In the instant case, the product as claimed can be made by another and materially different process such as one in which dielectric structure can be selectively deposited." However, the undersigned is unaware of any process currently known in the art for selectively depositing two different dielectric materials, one selectively etchable over the other, with an aligned hole through both materials.

If any issue arises, or if the Examiner has any suggestions for expediting allowance of



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JAN 23 2002  
TC 2000 MAIL ROOM

#1/Election  
of subject  
matter

ATTORNEY DOCKET NO. 93-C-077C1 (STMI01-93077)

U.S. SERIAL NO. 09/712,827

PATENT

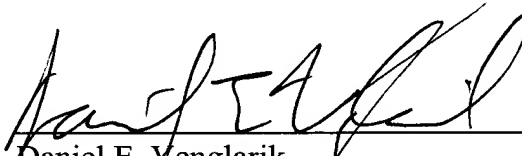
this application, the Applicant respectfully invites the Examiner to contact the undersigned at the telephone number indicated below or at *dvenglarik@novakov.com*.

The Commissioner is hereby authorized to charge any additional fees connected with this communication or credit any overpayment to Deposit Account No. 50-0208.

Respectfully submitted,

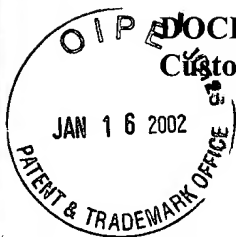
NOVAKOV DAVIS & MUNCK, P.C.

Date: 11-13-01

  
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**CERTIFICATE OF MAILING BY FIRST CLASS MAIL**

Sir:

The undersigned hereby certifies that the following documents:

1. Response to Restriction Requirement; and
2. A postcard receipt;

relating to the above application, were deposited as "First Class Mail" with the United States Postal Service, addressed to Box NON-FEE AMENDMENT, Commissioner for Patents, Washington, D.C. 20231, on November 13, 2001.

Date: 11/13/01

Kathy Longenecker  
Mailer

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